

V_{RSM} V_{RRM}	I_{FRMS} (maximum values for continuous operation)			
	130 A	130 A	300 A	300 A
V	I_{FAV} (sin. 180; $T_{case} = \dots^\circ\text{C}$; 50 Hz)			
	60 A (94 °C)	60 A (94 °C)	160 A (86 °C)	160 A (86 °C)
400	—	—	SKFH 110 /04..	—
800	SKFH 40/08	SKFH 60/08..	SKFH 110 /08..	SKKD 160 M 08
1000	SKFH 40/10	SKFH 60/10..	SKFH 110 /10..	SKKD 160 M 10
1200	SKFH 40/12	SKFH 60/12..	SKFH 110 /12..	SKKD 160 M 12
1400	—	—	—	SKKD 160 M 14

Symbol	Conditions	SKFH 40 ¹⁾ SKFH 60 ¹⁾	SKKD 160 M SKFH 110 ¹⁾
I_{FAV}	sin. 180; $T_{case} = 85^\circ\text{C}$	73 A	163 A
I_{FSM}	$T_{vj} = 25^\circ\text{C}$	1800 A	7000 A
	$T_{vj\max}$	1500 A	6000 A
i^2t	$T_{vj} = 25^\circ\text{C}$	16000 A ² s	245000 A ² s
	$T_{vj\max}$	11000 A ² s	180000 A ² s
t_{rr}	$T_{vj} = 25^\circ\text{C}$; $I_F = 1\text{ A}$; $-di_F/dt = 15\text{ A}/\mu\text{s}$; $V_R = 30\text{ V}$	2 μs	2 μs
Q_{rr}	$T_{vj\max}$; $I_F = 100\text{ A}$; $-di_F/dt = 30\text{ A}/\mu\text{s}$; $V_R = 30\text{ V}$	65 μC	65 μC
I_{RM}		35 A	45 A
I_R	$T_{vj} = 25^\circ\text{C}$; $V_R = V_{RRM}$ $T_{vj\max}$; $V_R = V_{RRM}$	1 mA 10 mA	2 mA 50 mA
V_F	$T_{vj} = 25^\circ\text{C}$; $I_F = \dots\text{ A}$	1,6 V (200 A)	1,5 V (400 A)
$V_{(TO)}$	$T_{vj\max}$	1,0 V	1,25 V
r_T		2 m Ω	0,5 m Ω
R_{thjc}	per diode/per module	0,4/0,2 °C/W ²⁾	0,19/0,095 °C/W ²⁾
R_{thch}		0,2/0,1 °C/W	0,06/0,03 °C/W
T_{vj}		-40 ... +125 °C	-40 ... +130 °C
T_{stg}		-40 ... +125 °C	-40 ... +130 °C
V_{isol}	a. c. 50 Hz; r.m.s.; 1 s/1 min.	3000 V ~ /2500 V ~ ²⁾	
M_1	Case to heatsink	5 Nm/44 lb. in. ± 15 %	5 Nm/44 lb. in. ± 15 %
M_2	Busbars to terminals	3 Nm/26 lb. in. ± 15 %	9 Nm/80 lb. in. ± 15 %
w	approx.	120 g	800 g
Case	→ page B 2-12	A 8	
Case	→ page B 2-32	SKKD SKFH	A 16 A 14

Fast Thyristor/ Diode Modules

SEMIPACK® 1

SKFH 40

Diode data¹⁾



SKFH 60

Diode data¹⁾

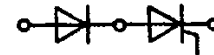
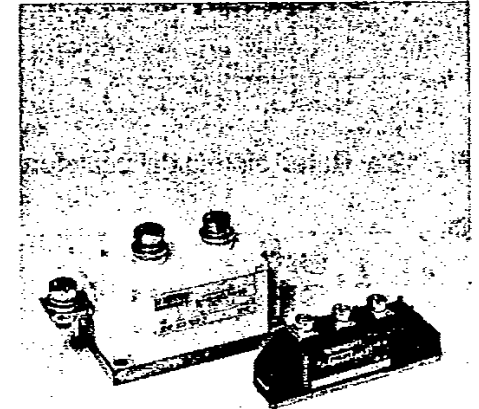


SEMIPACK® 3

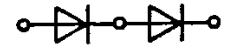
SKKD 160 M

SKFH 110

Diode data¹⁾



SKFH



SKKD

Features

- Heat transfer through ceramic isolated metal baseplate
- Hard soldered joints for high reliability
- SKKD 160 M: Precious metal pressure contacts
- UL recognized, file no. E 63 532

Typical Applications

- Self-commutated inverters
- DC choppers
- AC motor speed control
- Inductive heating
- Uninterruptible power supplies
- Electronic welders
- General power switching applications

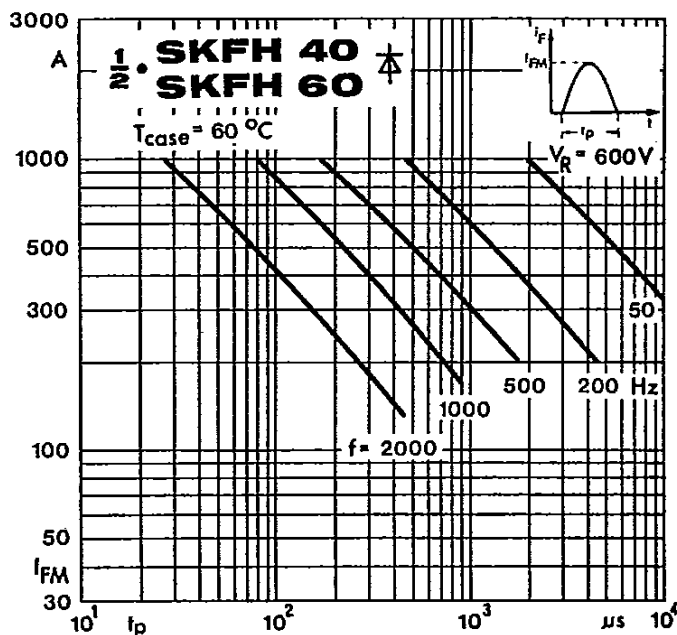


Fig. 12 a Rated sinusoidal peak forward current

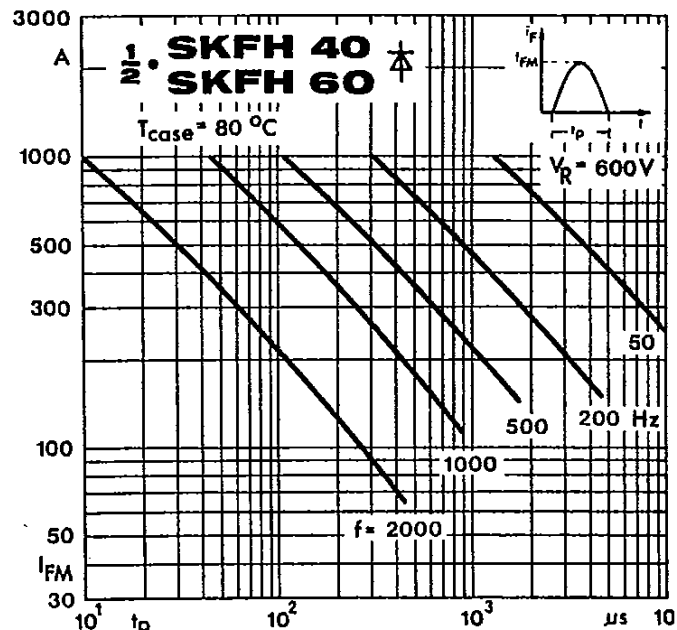


Fig. 12 b Rated sinusoidal peak forward current

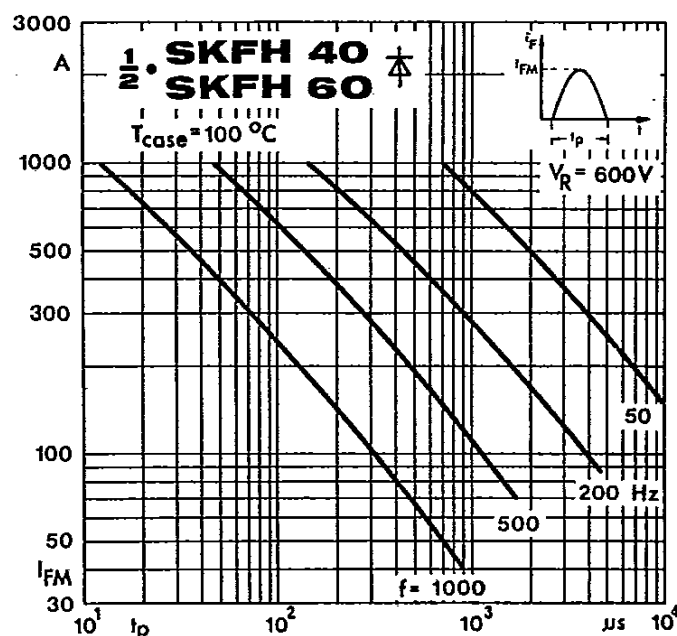


Fig. 12 c Rated sinusoidal peak forward current

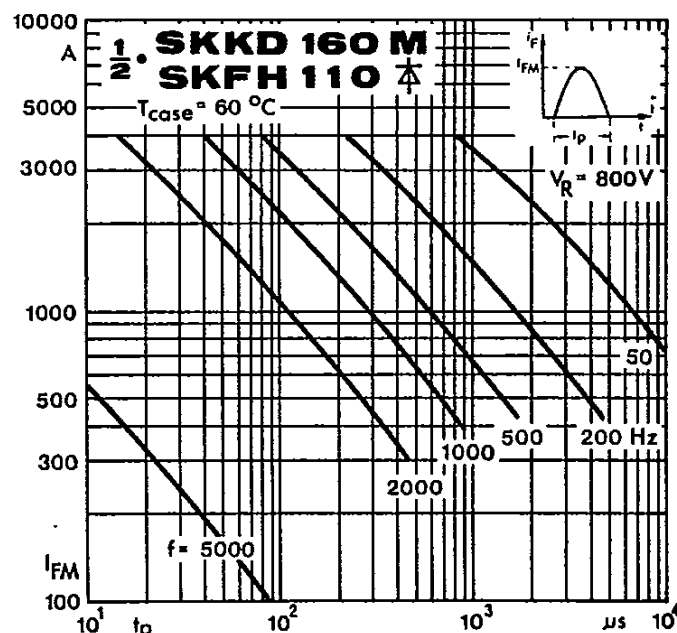


Fig. 12 d Rated sinusoidal peak forward current

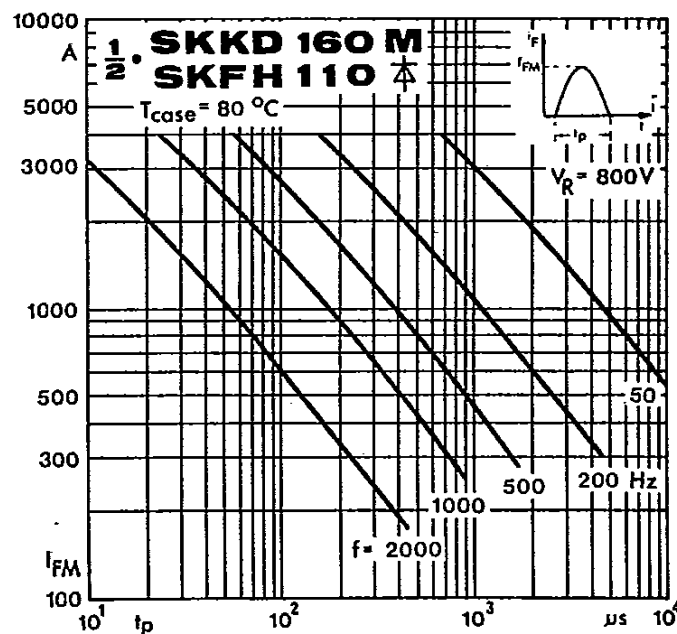


Fig. 12 e Rated sinusoidal peak forward current

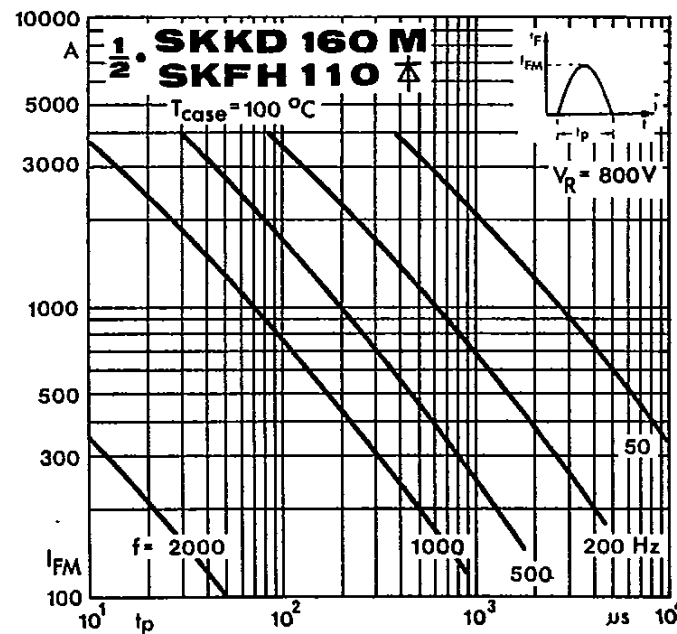


Fig. 12 f Rated sinusoidal peak forward current

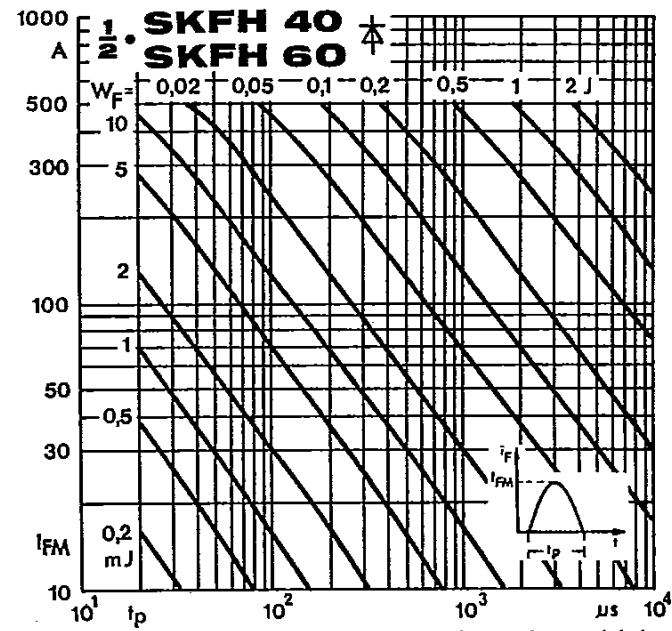


Fig. 13 a Forward energy dissipation, sinusoidal

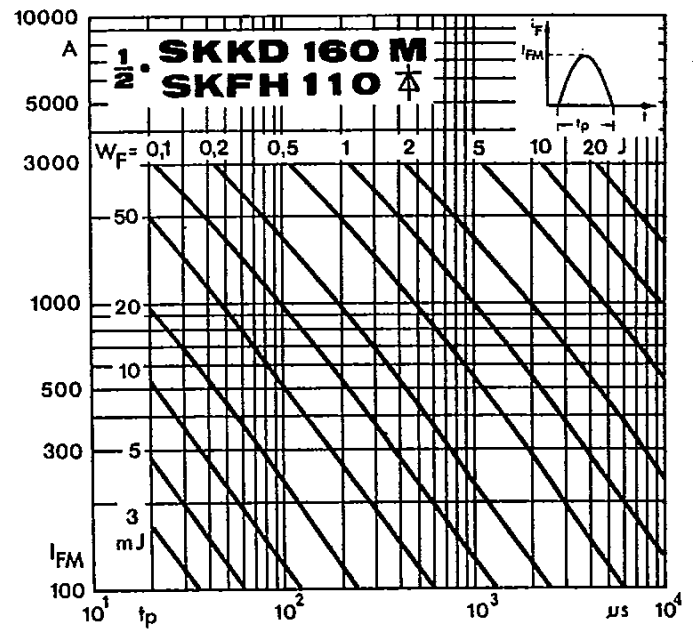


Fig. 13 b Forward energy dissipation, sinusoidal

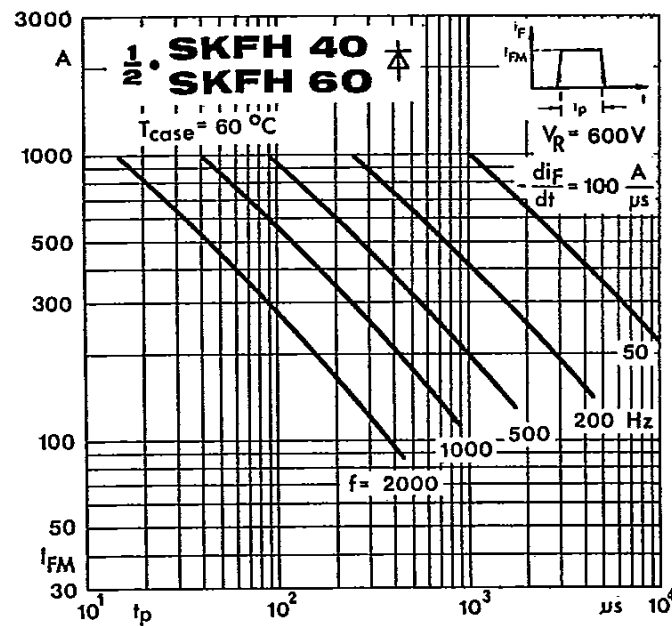


Fig. 14 a Rated rectangular peak forward current

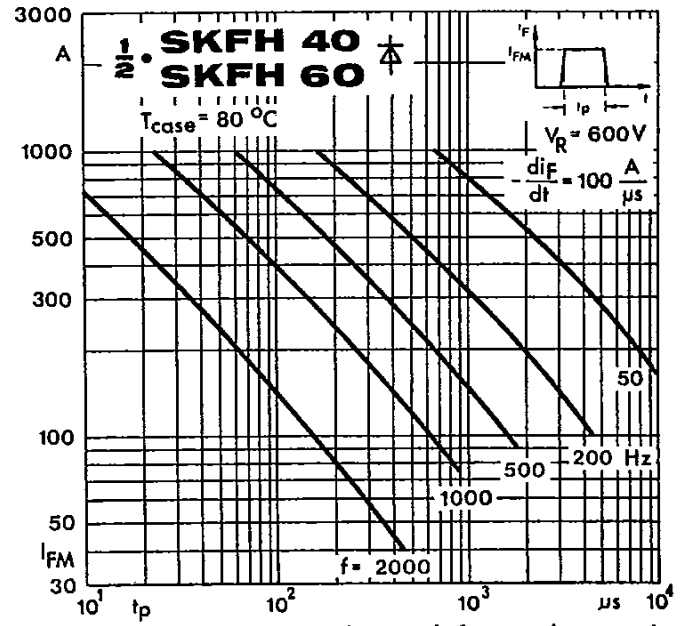


Fig. 14 b Rated rectangular peak forward current

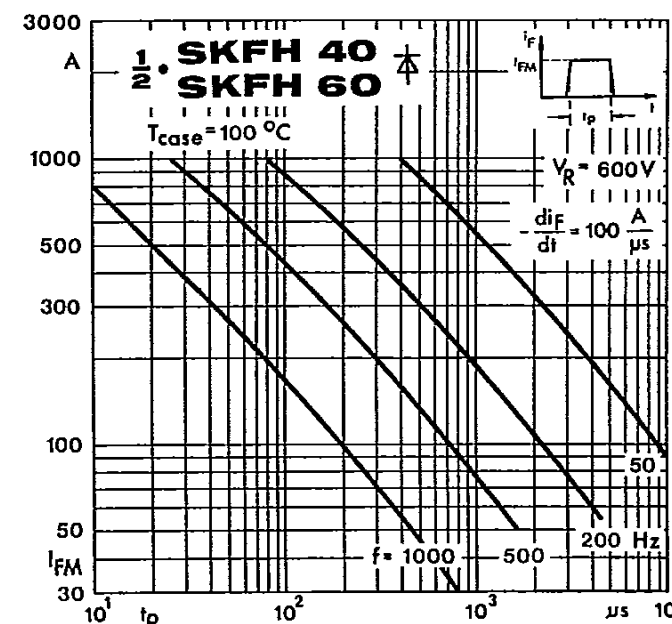


Fig. 14 c Rated rectangular peak forward current

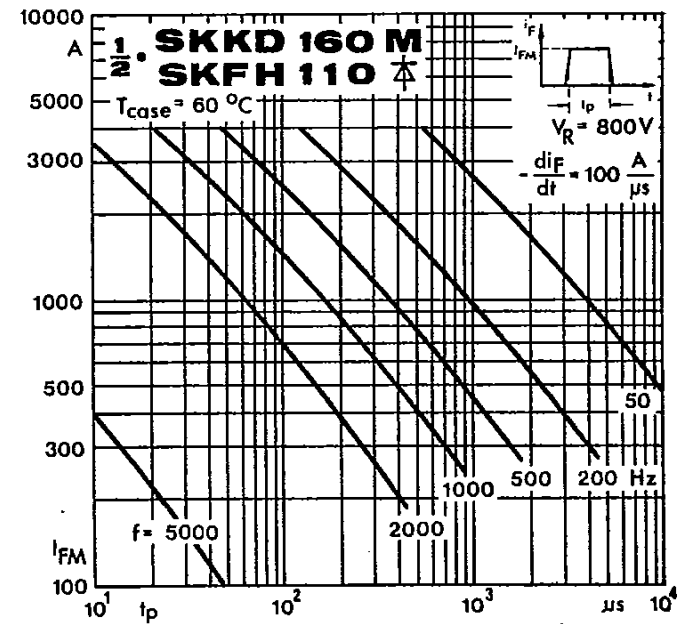


Fig. 14 d Rated rectangular peak forward current

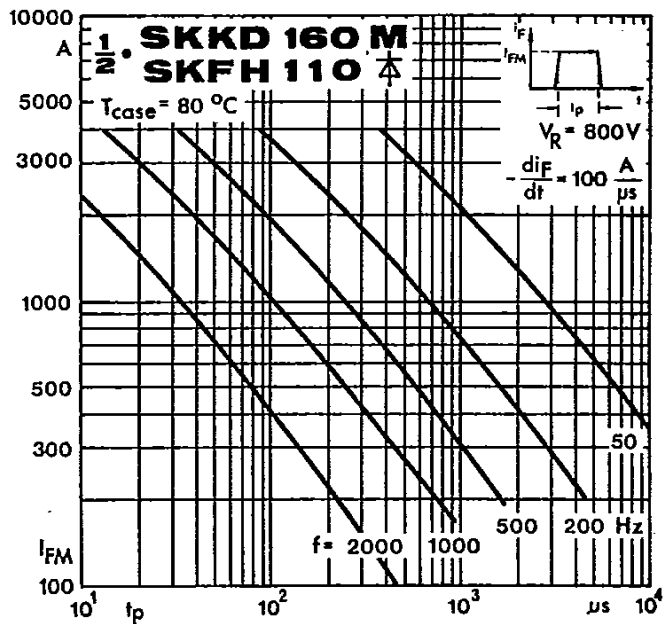


Fig. 14 e Rated rectangular peak forward current

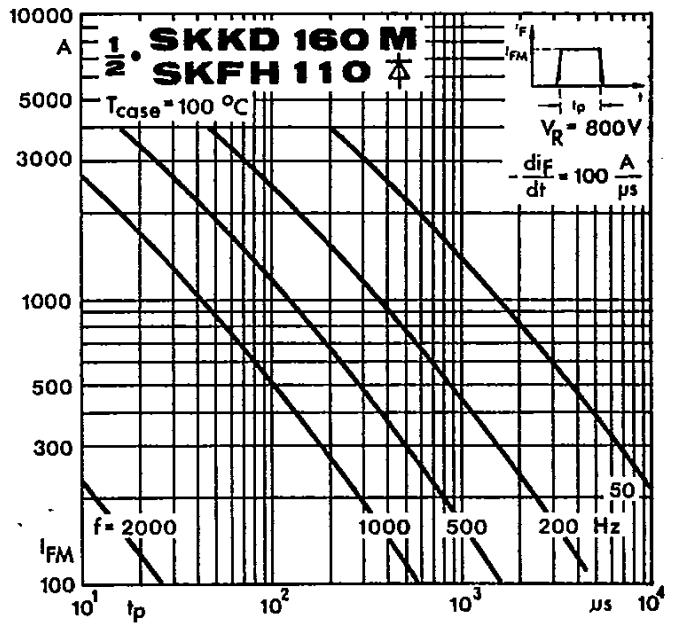


Fig. 14 f Rated rectangular peak forward current

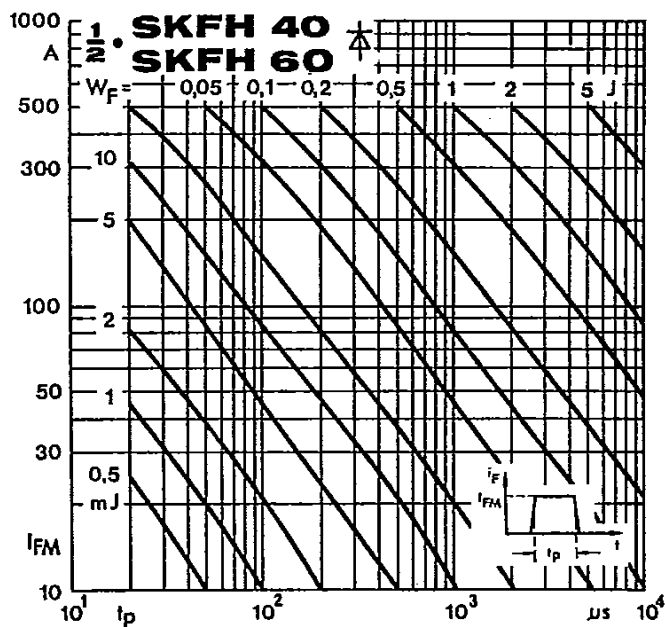


Fig. 15 a Forward energy dissipation, rectangular

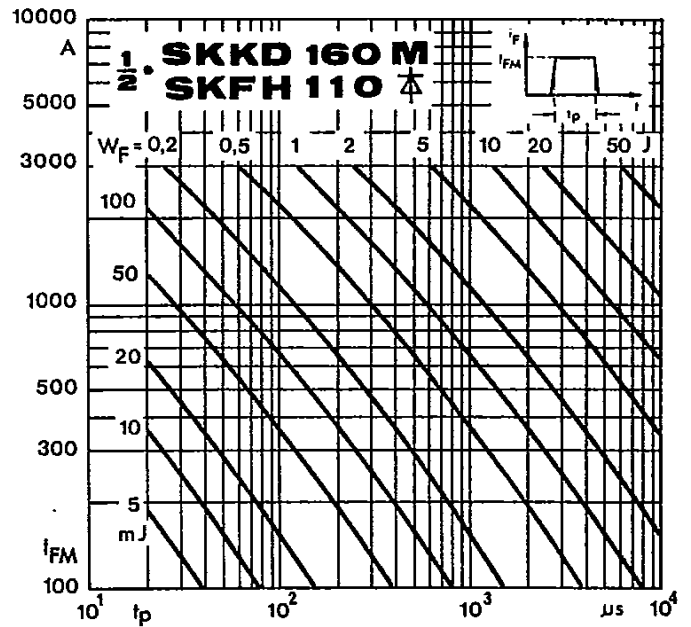


Fig. 15 b Forward energy dissipation, rectangular

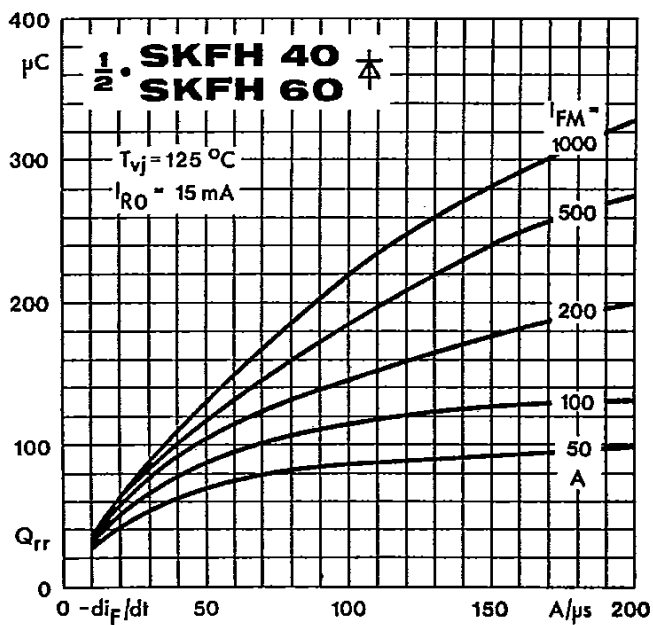


Fig. 16 a Recovered charge vs. current decrease

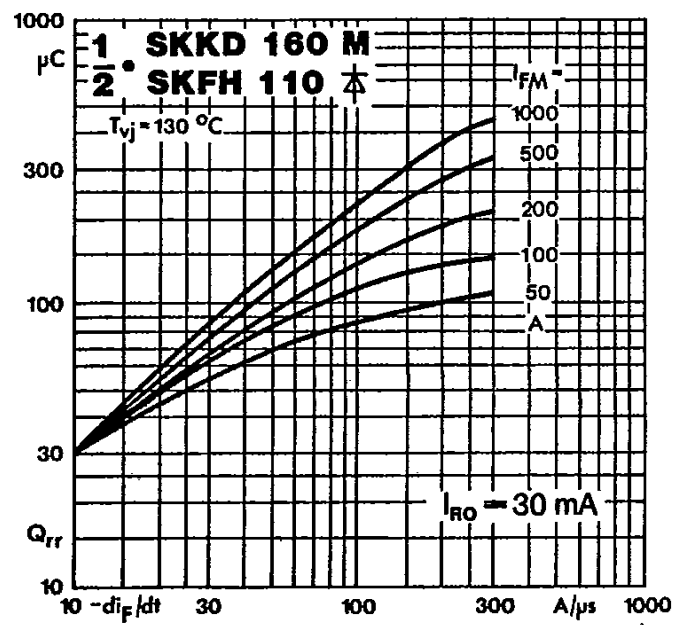


Fig. 16 b Recovered charge vs. current decrease

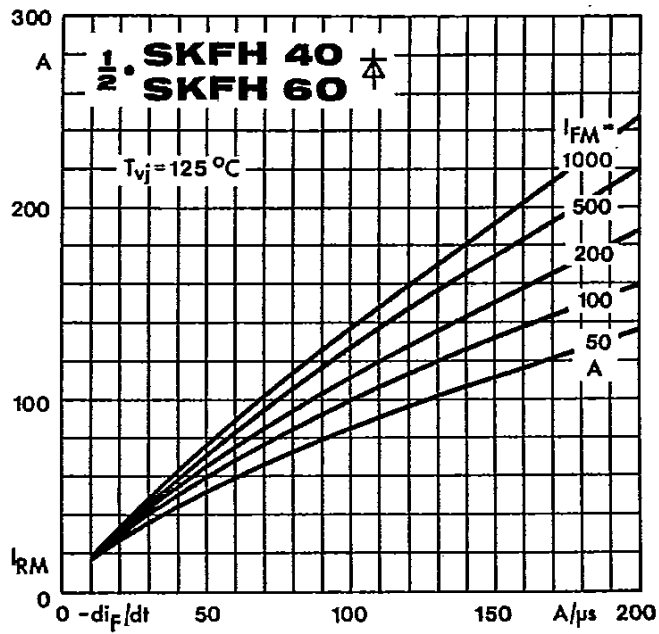


Fig. 17 a Peak recovery current vs. current decrease

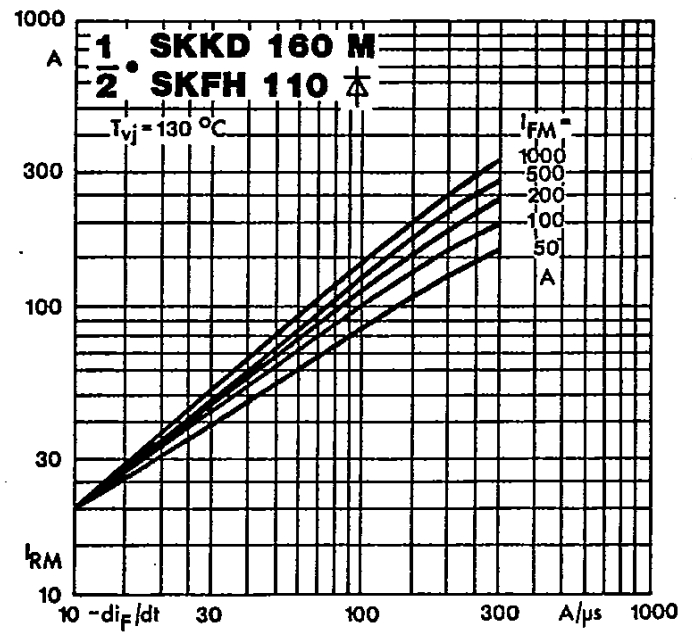


Fig. 17 b Peak recovery current vs. current decrease

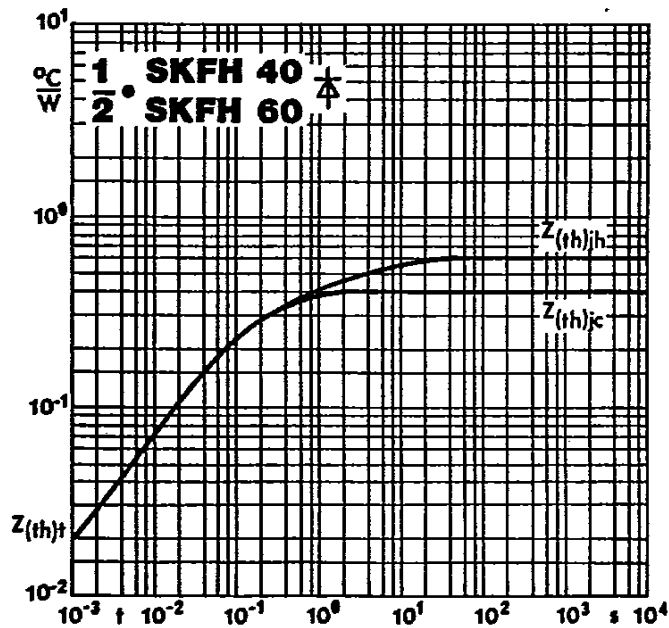


Fig. 18 a Transient thermal impedance vs. time

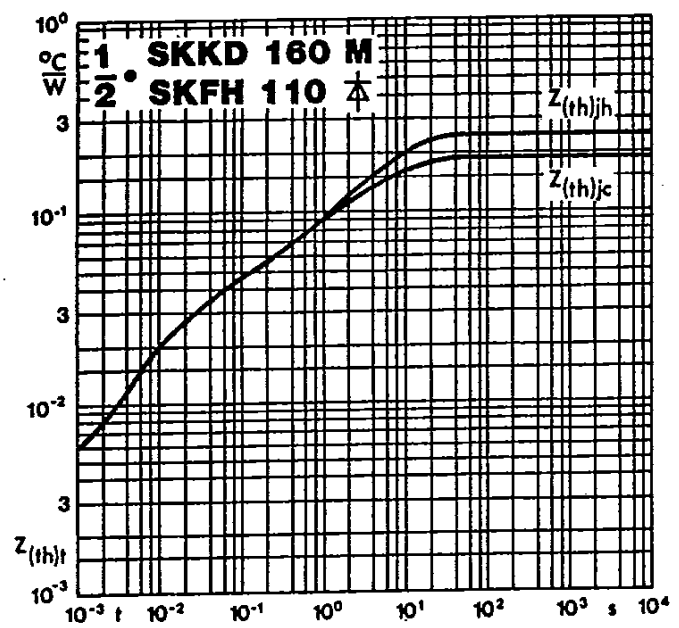


Fig. 18 b Transient thermal impedance vs. time

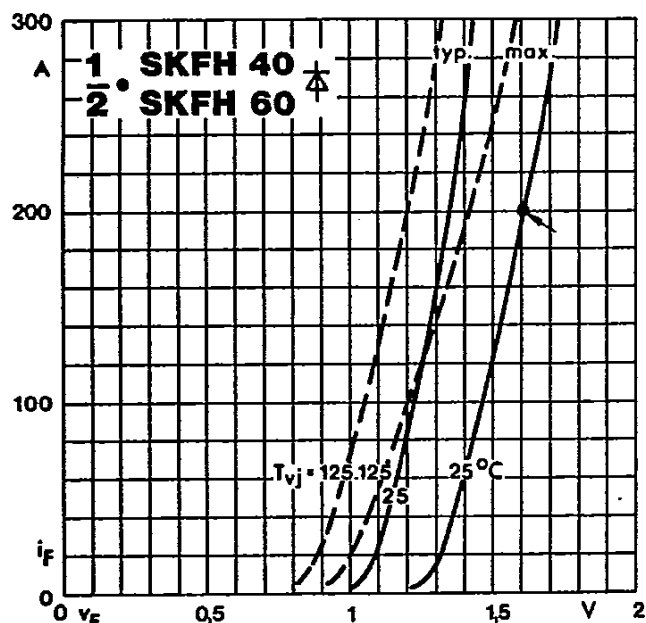


Fig. 19 a Forward characteristics

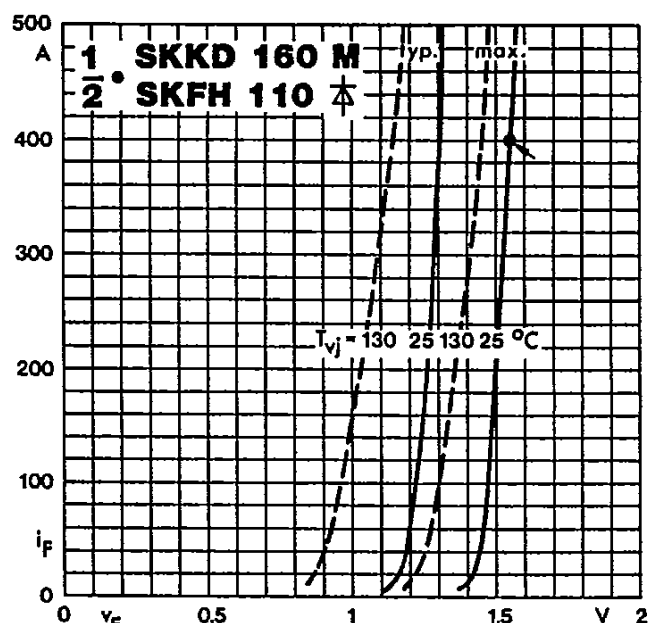


Fig. 19 b Forward characteristics

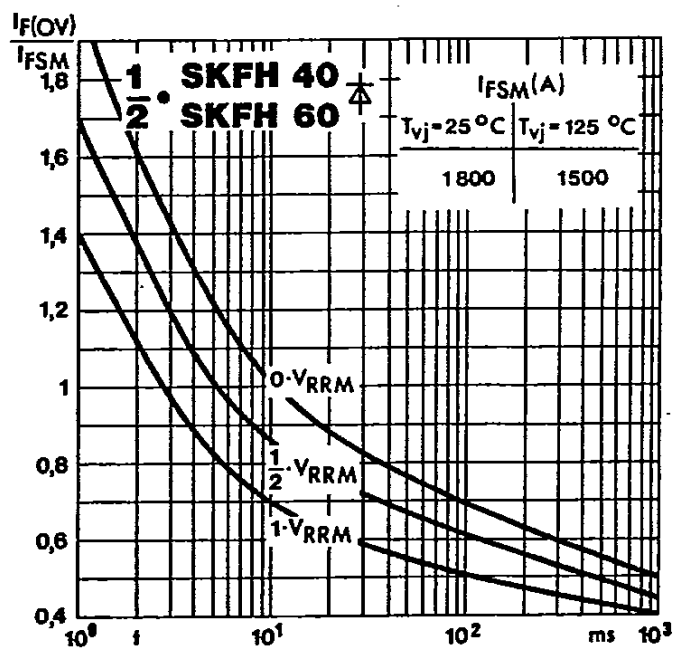


Fig. 20 a Surge overload current vs. time

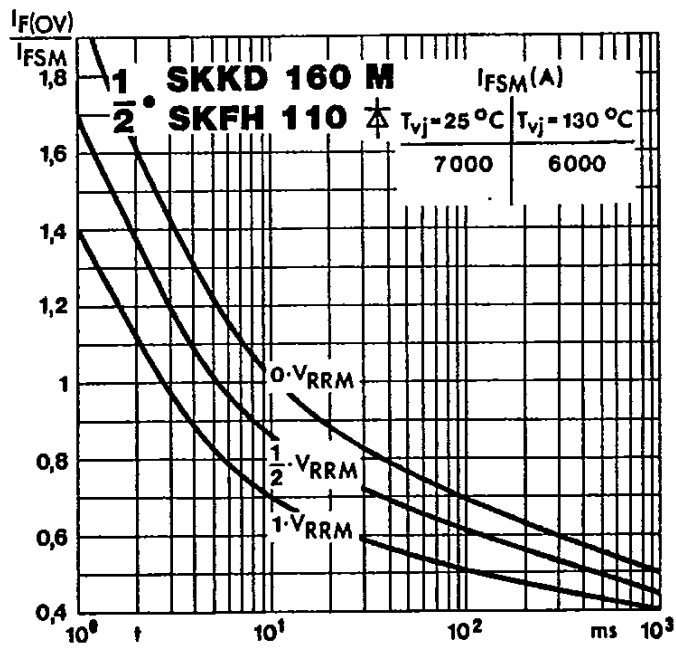


Fig. 20 b Surge overload current vs. time